

# LT3073 Die thickness update with Thermal Parameter Change.

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# LT3073 Die Thickness Update with Thermal Parameter Change

<b>PCB:</b>	<b>4L Demo Board</b>				
<b>Device:</b>	<b>LT3073</b>	<b>T<sub>ambient</sub> (°C) =</b>	<b>25C</b>		
<b>Die thickness (mm)</b>	<b>Die</b>	<b>P<sub>loss</sub> (W)</b>	<b>θ<sub>JA</sub> (K/W)</b>	<b>θ<sub>JCtop</sub> (K/W)</b>	<b>θ<sub>JCbot</sub> (K/W)</b>
0.2	U1	2.25	38	50.00	5.00
0.45			37.10	27.00	4.50
	<b>Total Power:</b>	<b>2.25</b>			